


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

| | | |
|----------------------|---|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCI No. | ADG/22/13511 | |
| 1.3 Title of PCI | Die thickness change for ECMF4-2450A60N10 | |
| 1.4 Product Category | ECMF4-2450A60N10 | |
| 1.5 Issue date | 2022-07-01 | |

2. PCI Team

| | |
|---------------------------|-------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | KRISZTINA NEMETH |
| 2.1.2 Phone | +49 89460062210 |
| 2.1.3 Email | krisztina.nemeth@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Stephane CHAMARD |
| 2.1.2 Marketing Manager | Philippe LEGER |
| 2.1.3 Quality Manager | Jean-Paul REBRASSE |

3. Change

| | | |
|---------------------|--|-----------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Wafer Fab (Process) | Backside finish modification except for wafer for sale: change final wafer thickness | STMicroelectronics Tours - France |

4. Description of change

| | | |
|---|---|---|
| | Old | New |
| 4.1 Description | Thinnest die (part of ECMF4-2450A60N10) is of 90µm thickness. | Increase the thickness of the thinnest die (part of ECMF4-2450A60N10) from 90µm to 125µm. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No | |

5. Reason / motivation for change

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|----------------------|--|
| 5.1 Motivation | In the frame of production yields optimization, STMicroelectronics has decided to increase the thickness of the thinnest die (part of ECMF4-2450A60N10) from 90µm to 125µm. New die thickness is already qualified for other product ECMF4-40A100N10 (directly qualified with this new 125µm thickness). |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT |

6. Marking of parts / traceability of change

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|-----------------|--|
| 6.1 Description | Traceability of the change will be ensured by Finished Good/Type print on carton labels. |
|-----------------|--|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2022-06-20 |
| 7.2 Intended start of delivery | 2022-10-07 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | | | |
|--|----------------------------|------------|------------|
| 8.1 Description | 13511 18054QRP v2.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2022-07-01 |

| 9. Attachments (additional documentations) | | |
|---|--|--|
| 13511 Public product.pdf 13511 ECMF4-2450A60N10 die thickness.pdf 13511 18054QRP v2.pdf | | |

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | ECMF4-2450A60N10 | |

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